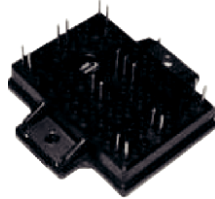


## Dual Mode PFC, 60 A


**EMIPAK2**
**FEATURES**

- NPT Warp2 PFC IGBT with low  $V_{CE(ON)}$
- Silicon carbide PFC diode
- Antiparallel FRED Pt® fast recovery
- Integrated thermistor
- Square RBSOA
- Operating frequency 60 kHz to 150 kHz
- Low internal inductances
- Low switching loss
- UL approved file E78996
- Material categorization: For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT

PRODUCT SUMMARY	
$V_{CES}$	600 V
$V_{CE(ON)}$ typical at $I_C = 50$ A	1.8 V
$I_C$ at $T_C = 98$ °C	50 A
Package	EMIPAK2
Circuit	Dual Mode PFC

**DESCRIPTION**

VS-EMG050J60N is an integrated solution for dual stage PFC converter in a single package. The EMIPAK2 package is easy to use thanks to the solderable terminals and provides improved thermal performance thanks to the exposed substrate. The optimized layout also helps to minimize stray parameters, allowing for better EMI performance.

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Maximum operating junction temperature	$T_J$		150	°C
Storage temperature range	$T_{Stg}$		- 40 to 125	
RMS isolation voltage	$V_{ISOL}$	$T_J = 25$ °C, all terminals shorted, $f = 50$ Hz, $t = 1$ s	3500	V
PFC IGBT Q1 - Q2				
Collector to emitter voltage	$V_{CES}$		600	V
Gate to emitter voltage	$V_{GES}$		20	
Pulsed collector current	$I_{CM}$		150	A
Clamped inductive load current	$I_{LM}^{(1)}$		150	
Continuous collector current	$I_C$	$T_C = 25$ °C	88	
		$T_C = 80$ °C	60	
Power dissipation	$P_D$	$T_C = 25$ °C	338	W
		$T_C = 80$ °C	189	
ANTIPARALLEL DIODE D1 - D2				
Diode continuous forward current	$I_F$	$T_C = 25$ °C	16	A
		$T_C = 80$ °C	11	
Single pulse forward current	$I_{FSM}$	10 ms sine or 6 ms rectangular pulse, $T_J = 25$ °C	59	
Power dissipation	$P_D$	$T_C = 25$ °C	29	W
		$T_C = 80$ °C	16	
PFC DIODE D3 - D4				
Repetitive peak reverse voltage	$V_{RRM}$		600	V
Diode continuous forward current	$I_F$	$T_C = 25$ °C	25	A
		$T_C = 80$ °C	17	
Single pulse forward current	$I_{FSM}$	10 ms sine or 6 ms rectangular pulse, $T_J = 25$ °C	140	
Power dissipation	$P_D$	$T_C = 25$ °C	74	W
		$T_C = 80$ °C	41	

**Notes**

- Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur.

<sup>(1)</sup>  $V_{CC} = 400$  V,  $V_{GE} = 15$  V,  $L = 500$   $\mu$ H,  $R_g = 22$   $\Omega$ ,  $T_J = 150$  °C



<b>ELECTRICAL SPECIFICATIONS</b> ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
<b>PFC IGBT Q1 - Q2</b>						
Collector to emitter breakdown voltage	$BV_{CES}$	$V_{GE} = 0\text{ V}, I_C = 500\text{ }\mu\text{A}$	600	-	-	V
Temperature coefficient of breakdown voltage	$\Delta BV_{CES}/\Delta T_J$	$V_{GE} = 0\text{ V}, I_C = 500\text{ }\mu\text{A}$ ( $25\text{ }^\circ\text{C}$ to $125\text{ }^\circ\text{C}$ )	-	0.1	-	V/ $^\circ\text{C}$
Collector to emitter voltage	$V_{CE(ON)}$	$V_{GE} = 15\text{ V}, I_C = 27\text{ A}$	-	1.44	1.75	V
		$V_{GE} = 15\text{ V}, I_C = 50\text{ A}$	-	1.8	2.1	
		$V_{GE} = 15\text{ V}, I_C = 27\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	1.7	2.05	
		$V_{GE} = 15\text{ V}, I_C = 50\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	2.2	2.5	
Gate threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}, I_C = 250\text{ }\mu\text{A}$	2.9	3.9	5.3	
Temperature coefficient of threshold voltage	$\Delta V_{GE(th)}/\Delta T_J$	$V_{CE} = V_{GE}, I_C = 1\text{ mA}$ ( $25\text{ }^\circ\text{C}$ to $125\text{ }^\circ\text{C}$ )	-	- 10	-	mV/ $^\circ\text{C}$
Forward transconductance	$g_{fe}$	$V_{CE} = 20\text{ V}, I_C = 50\text{ A}$	-	95	-	s
Transfer characteristics	$V_{GE}$	$V_{CE} = 20\text{ V}, I_C = 50\text{ A}$	-	5.9	-	V
Zero gate voltage collector current	$I_{CES}$	$V_{GE} = 0\text{ V}, V_{CE} = 600\text{ V}$	-	3	100	$\mu\text{A}$
		$V_{GE} = 0\text{ V}, V_{CE} = 600\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	0.170	3	mA
Gate to emitter leakage current	$I_{GES}$	$V_{GE} = \pm 20\text{ V}, V_{CE} = 0\text{ V}$	-		$\pm 200$	nA
<b>ANTIPARALLEL DIODE D1 - D2</b>						
Forward voltage drop	$V_F$	$I_F = 20\text{ A}$	-	2.19	2.4	V
		$I_F = 20\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	1.93	2.15	
<b>PFC DIODE D3 - D4</b>						
Cathode to anode breakdown voltage	$V_{BR}$	$I_R = 500\text{ }\mu\text{A}$	600	-	-	V
Reverse leakage current	$I_{RM}$	$V_R = 600\text{ V}$	-	27	250	$\mu\text{A}$
		$V_R = 600\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	0.1	1	mA
Forward voltage drop	$V_F$	$I_F = 10\text{ A}$	-	1.34	1.63	V
		$I_F = 10\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	1.36	1.65	

<b>SWITCHING CHARACTERISTICS</b> ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
<b>PFC IGBT Q1 - Q2 (WITH FREEWHEELING D3 - D4 PFC DIODE)</b>						
Total gate charge (turn-on)	$Q_g$	$I_C = 70\text{ A}$ $V_{CC} = 400\text{ V}$ $V_{GE} = 15\text{ V}$	-	480	720	nC
Gate to emitter charge (turn-on)	$Q_{ge}$		-	82	164	
Gate to collector charge (turn-on)	$Q_{gc}$		-	160	260	
Turn-on switching loss	$E_{ON}$	$I_C = 50\text{ A}$ $V_{CC} = 400\text{ V}$ $V_{GE} = 15\text{ V}$ $R_g = 4.7\text{ }\Omega$ $L = 500\text{ }\mu\text{H}$ $T_J = 25\text{ }^\circ\text{C}^{(1)}$	-	0.155	-	mJ
Turn-off switching loss	$E_{OFF}$		-	0.471	-	
Total switching loss	$E_{TOT}$		-	0.626	-	
Turn-on delay time	$t_{d(on)}$			-	196	-
Rise time	$t_r$	-		29	-	
Turn-off delay time	$t_{d(off)}$	-		220	-	
Fall time	$t_f$	-		67	-	



<b>SWITCHING CHARACTERISTICS</b> ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on switching loss	$E_{ON}$	$I_C = 50\text{ A}$ $V_{CC} = 400\text{ V}$ $V_{GE} = 15\text{ V}$	-	0.182	-	mJ
Turn-off switching loss	$E_{OFF}$		-	0.615	-	
Total switching loss	$E_{TOT}$		-	0.797	-	
Turn-on delay time	$t_{d(on)}$	$R_g = 4.7\text{ }\Omega$ $L = 500\text{ }\mu\text{H}$ $T_J = 125\text{ }^\circ\text{C}^{(1)}$	-	198	-	ns
Rise time	$t_r$		-	29	-	
Turn-off delay time	$t_{d(off)}$		-	227	-	
Fall time	$t_f$		-	75	-	
Input capacitance	$C_{ies}$	$V_{GE} = 0\text{ V}$ $V_{CC} = 30\text{ V}$ $f = 1\text{ MHz}$	-	9500	-	pF
Output capacitance	$C_{oes}$		-	780	-	
Reverse transfer capacitance	$C_{res}$		-	116	-	
Reverse bias safe operating area	RBSOA	$T_J = 150\text{ }^\circ\text{C}$ , $I_C = 150\text{ A}$ $V_{CC} = 400\text{ V}$ , $V_P = 600\text{ V}$ $R_g = 22\text{ }\Omega$ , $V_{GE} = 15\text{ V to }0\text{ V}$	Fullsquare			

<b>ANTIPARALLEL DIODE D1 - D2</b>						
Diode reverse recovery time	$t_{rr}$	$V_R = 200\text{ V}$ $I_F = 20\text{ A}$ $di/dt = 500\text{ A}/\mu\text{s}$ , $T_J = 25\text{ }^\circ\text{C}$	-	65	110	ns
Diode peak reverse current	$I_{rr}$		-	11	15	A
Diode reverse charge	$Q_{rr}$		-	350	825	nC
Diode reverse recovery time	$t_{rr}$	$V_R = 200\text{ V}$ $I_F = 20\text{ A}$ $di/dt = 500\text{ A}/\mu\text{s}$ , $T_J = 125\text{ }^\circ\text{C}$	-	83	130	ns
Diode peak reverse current	$I_{rr}$		-	15	20	A
Diode reverse charge	$Q_{rr}$		-	587	1300	nC

<b>PFC DIODE D3 - D4</b>						
Diode reverse recovery time	$t_{rr}$	$V_R = 200\text{ V}$ $I_F = 10\text{ A}$ $di/dt = 200\text{ A}/\mu\text{s}$ , $T_J = 25\text{ }^\circ\text{C}$	-	43	-	ns
Diode peak reverse current	$I_{rr}$		-	2.13	-	A
Diode reverse charge	$Q_{rr}$		-	45.5	-	nC
Diode reverse recovery time	$t_{rr}$	$V_R = 200\text{ V}$ $I_F = 10\text{ A}$ $di/dt = 200\text{ A}/\mu\text{s}$ , $T_J = 125\text{ }^\circ\text{C}$	-	44	-	ns
Diode peak reverse current	$I_{rr}$		-	2.14	-	A
Diode reverse charge	$Q_{rr}$		-	46.5	-	nC

**Note**

(1) Energy losses include “tail” and diode reverse recovery.

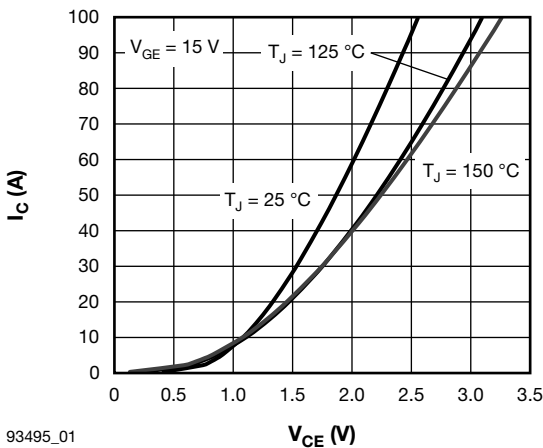
<b>THERMISTOR ELECTRICAL CHARACTERISTICS</b> ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Resistance	$R_{25}$		4500	5000	5500	$\Omega$
	$R_{100}$	$T_J = 100\text{ }^\circ\text{C}$	468	493	518	
B value	B	$T_J = 25\text{ }^\circ\text{C}/T_J = 50\text{ }^\circ\text{C}$	3206	3375	3544	K



THERMAL AND MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS
Q1 - Q2 PFC IGBT - Junction to case thermal resistance (per switch)	$R_{thJC}$	-	-	0.37	°C/W
D1 - D2 AP diode - Junction to case thermal resistance (per diode)		-	-	4.29	
D3 - D4 PFC diode - Junction to case thermal resistance (per diode)		-	-	1.69	
Q1 - Q2 PFC IGBT - Case to sink thermal resistance (per switch)	$R_{thCS}^{(1)}$	-	0.31	-	
D1 - D2 AP diode - Case to sink thermal resistance (per diode)		-	3.66	-	
D3 - D4 PFC diode - Case to sink thermal resistance (per diode)		-	1.1	-	
Mounting torque (M4)		2	-	3	Nm
Weight		-	39	-	g

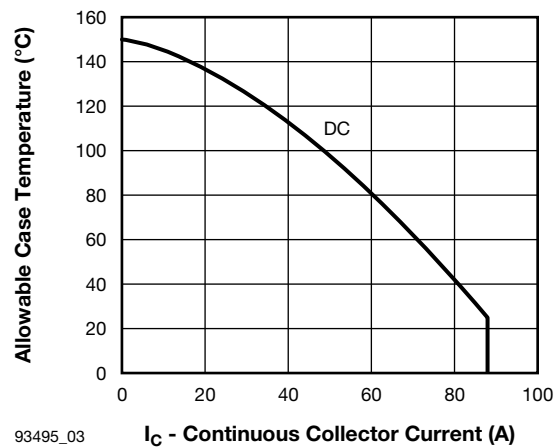
**Note**

(1) Mounting surface flat, smooth, and greased



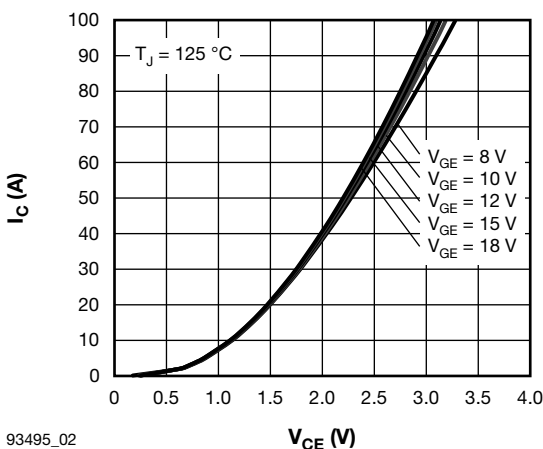
93495\_01

Fig. 1 - Typical PFC IGBT Output Characteristics



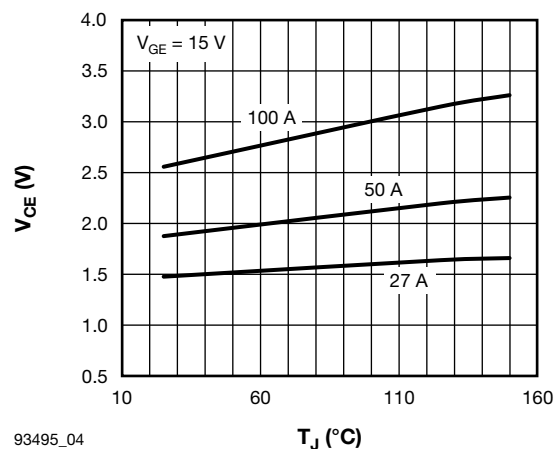
93495\_03

**$I_c$  - Continuous Collector Current (A)**  
Fig. 3 - Maximum DC PFC IGBT Collector Current vs. Case Temperature per Junction



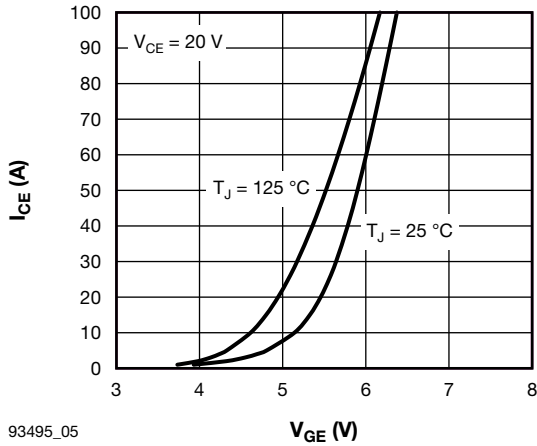
93495\_02

Fig. 2 - Typical PFC IGBT Output Characteristics



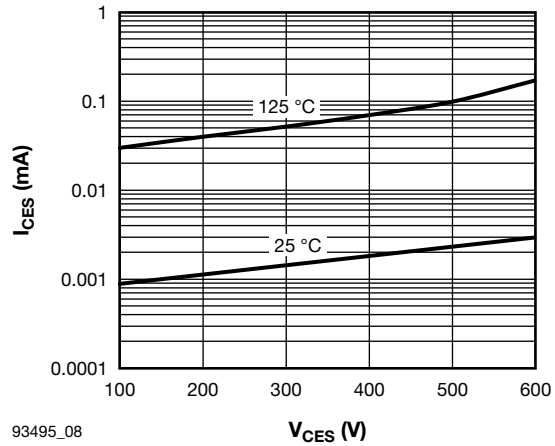
93495\_04

Fig. 4 - Typical PFC IGBT Collector to Emitter Voltage vs. Junction Temperature



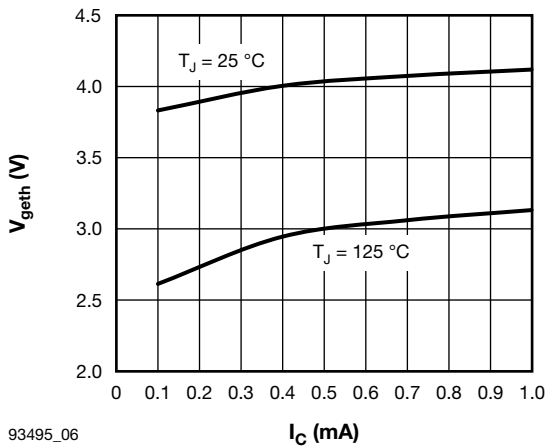
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Fig. 5 - Typical PFC IGBT Transfer Characteristics



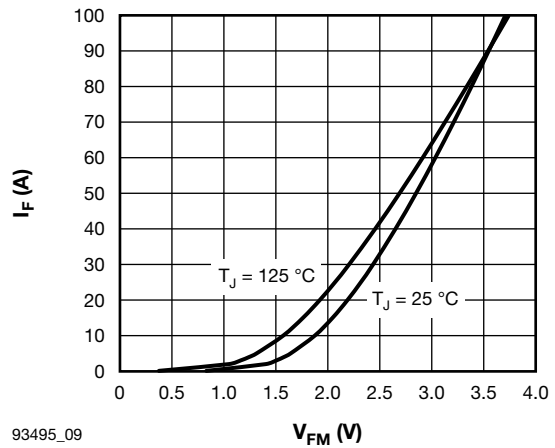
93495\_08

Fig. 8 - Typical PFC IGBT Zero Gate Voltage Collector Current



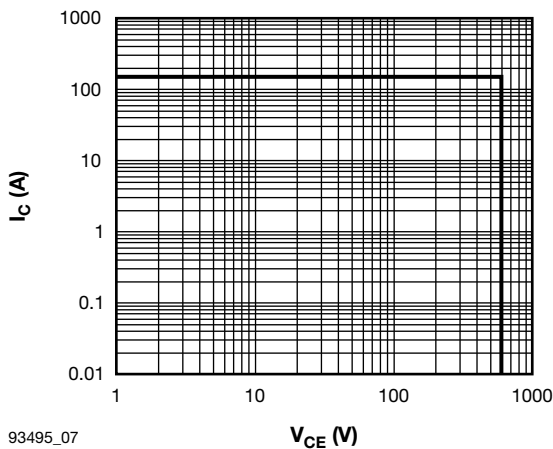
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Fig. 6 - Typical PFC IGBT Gate Threshold Voltage



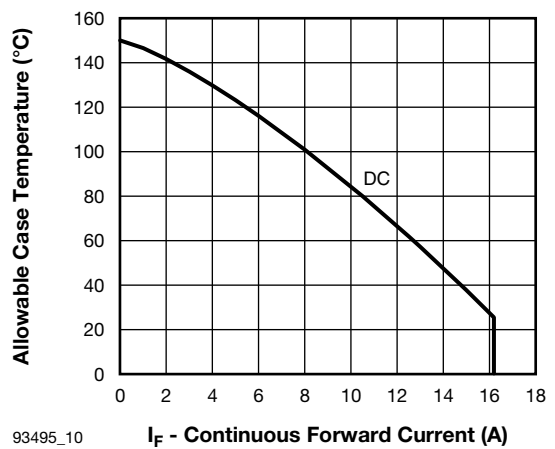
93495\_09

Fig. 9 - Typical Antiparallel Diode Forward Characteristics



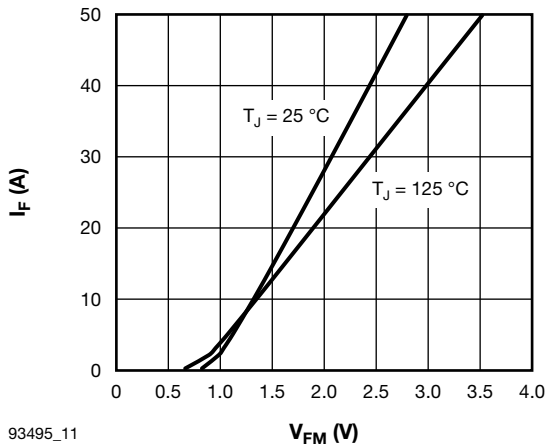
93495\_07

Fig. 7 - IGBT Reverse Bias SOA  
 $T_J = 150\text{ °C}$ ,  $V_{GE} = 15\text{ V}$ ,  $R_g = 22\ \Omega$



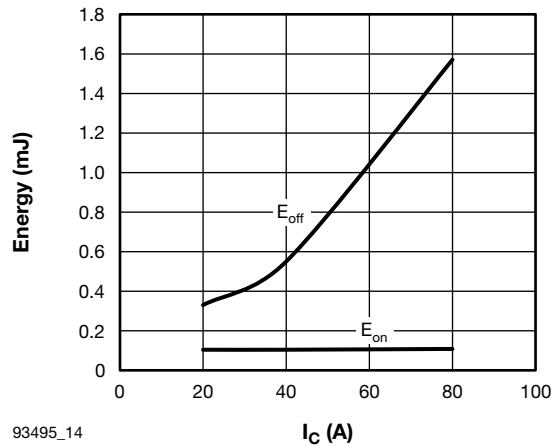
93495\_10

Fig. 10 - Maximum DC Antiparallel Diode Forward Current vs. Case Temperature per Junction



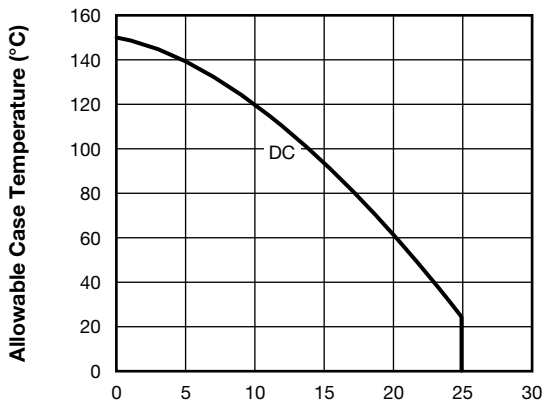
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Fig. 11 - Typical PFC Diode Forward Characteristics



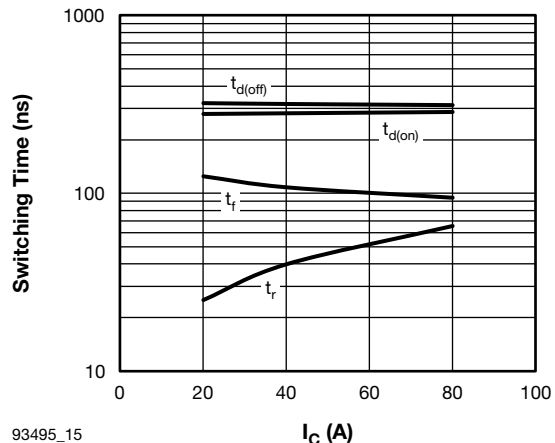
93495\_14

Fig. 14 - Typical PFC IGBT Energy Loss vs.  $I_C$   
(with Freewheeling D3 - D4 PFC Diode)  
 $T_J = 125\text{ }^\circ\text{C}$ ,  $V_{CC} = 400\text{ V}$ ,  $R_g = 4.7\text{ }\Omega$ ,  $V_{GE} = 15\text{ V}$ ,  $L = 500\text{ }\mu\text{H}$



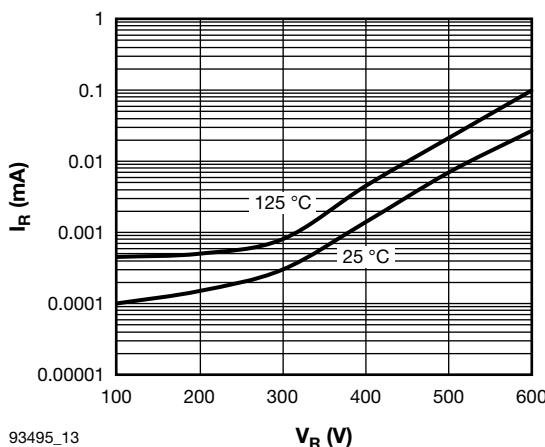
93495\_12

Fig. 12 - Maximum DC PFC Diode Forward Current vs. Case Temperature per Junction



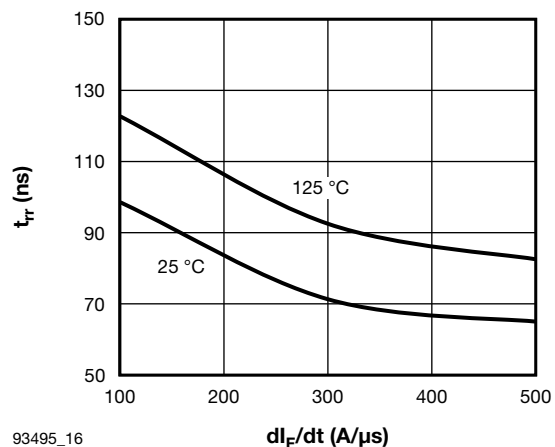
93495\_15

Fig. 15 - Typical PFC IGBT Switching Time vs.  $I_C$   
(with Freewheeling D3 - D4 PFC Diode)  
 $T_J = 125\text{ }^\circ\text{C}$ ,  $V_{CC} = 400\text{ V}$ ,  $R_g = 4.7\text{ }\Omega$ ,  $V_{GE} = 15\text{ V}$ ,  $L = 500\text{ }\mu\text{H}$



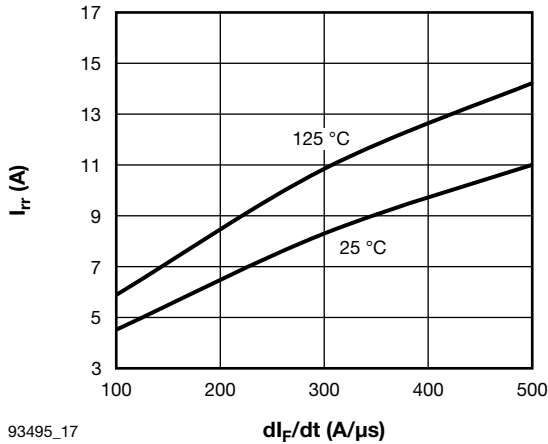
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Fig. 13 - Typical PFC Diode Reverse Leakage Current



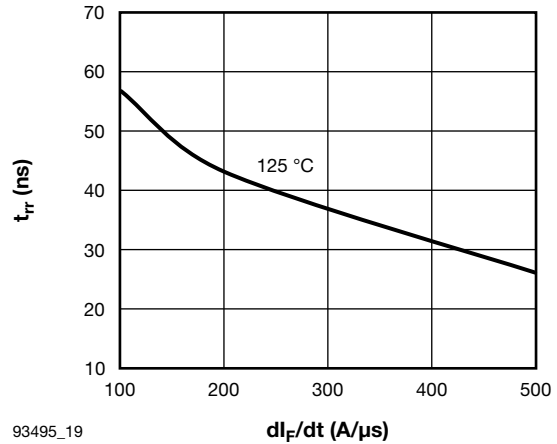
93495\_16

Fig. 16 - Typical Antiparallel Reverse Recovery Time vs.  $di_F/dt$   
 $V_R = 200\text{ V}$ ,  $I_F = 20\text{ A}$



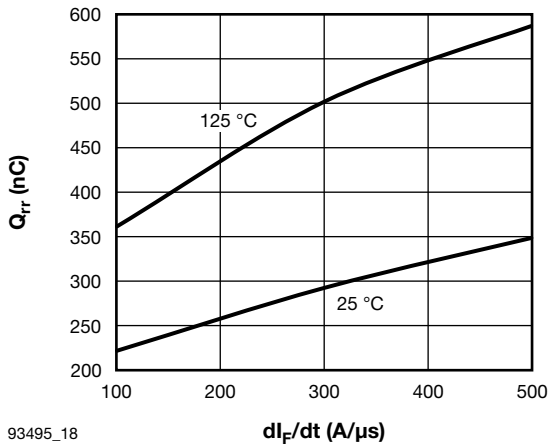
93495\_17

Fig. 17 - Typical Antiparallel Reverse Recovery Current vs.  $di_F/dt$   
 $V_R = 200\text{ V}$ ,  $I_F = 20\text{ A}$



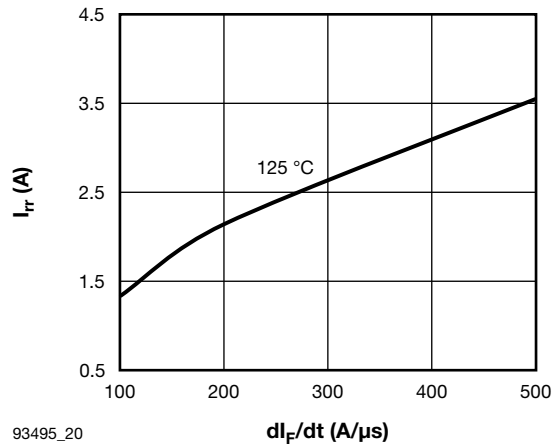
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Fig. 19 - Typical PFC Diode Reverse Recovery Time vs.  $di_F/dt$   
 $V_R = 200\text{ V}$ ,  $I_F = 10\text{ A}$



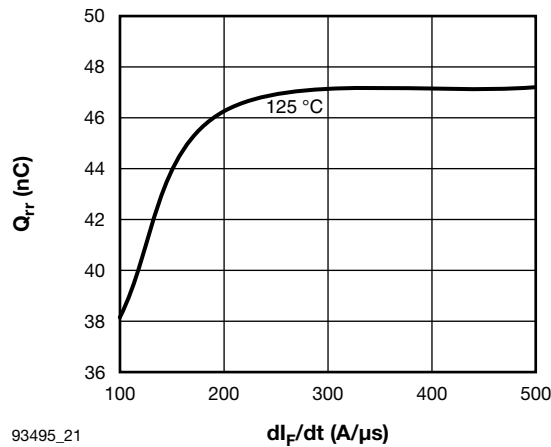
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Fig. 18 - Typical Antiparallel Reverse Recovery Charge vs.  $di_F/dt$   
 $V_R = 200\text{ V}$ ,  $I_F = 20\text{ A}$



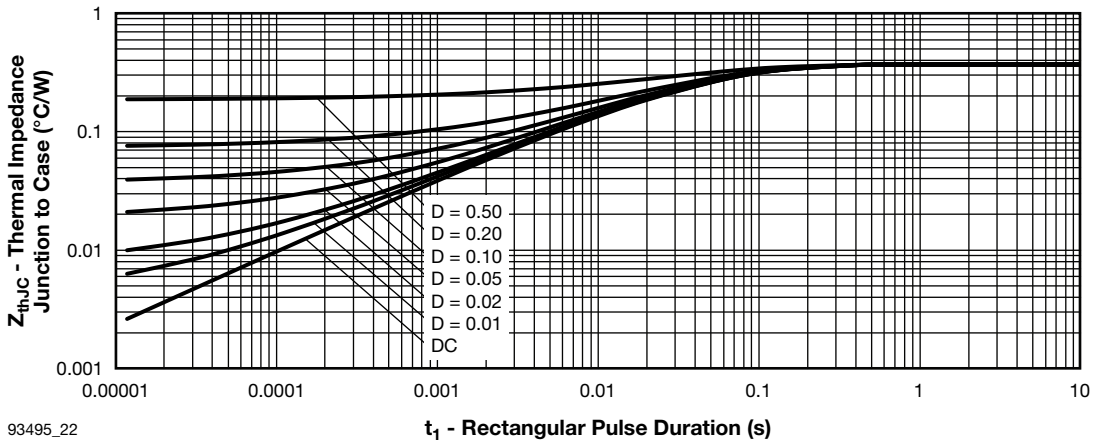
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Fig. 20 - Typical PFC Diode Reverse Recovery Current vs.  $di_F/dt$   
 $V_R = 200\text{ V}$ ,  $I_F = 10\text{ A}$



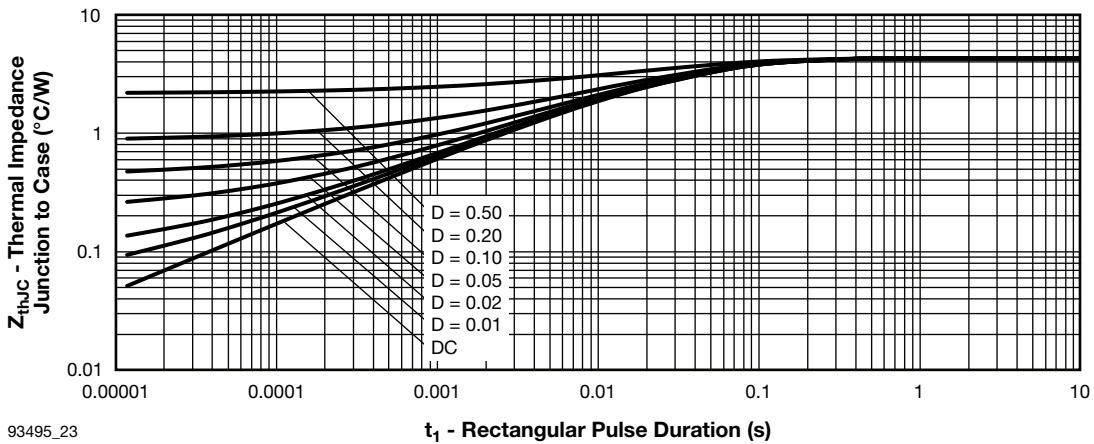
93495\_21

Fig. 21 - Typical PFC Diode Reverse Recovery Charge vs.  $di_F/dt$   
 $V_R = 200\text{ V}$ ,  $I_F = 10\text{ A}$



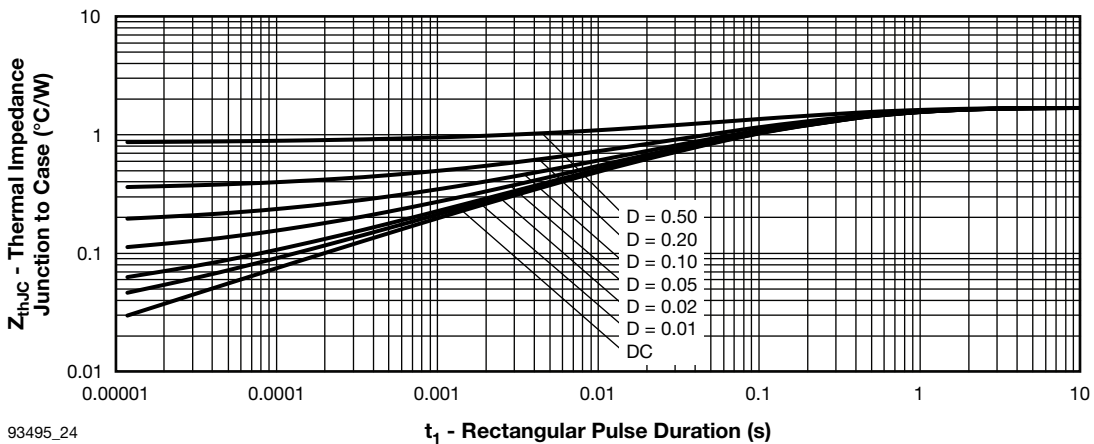
93495\_22

Fig. 22 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics (IGBT)



93495\_23

Fig. 23 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics (Antiparallel Diode)



93495\_24

Fig. 24 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics (PFC Diode)

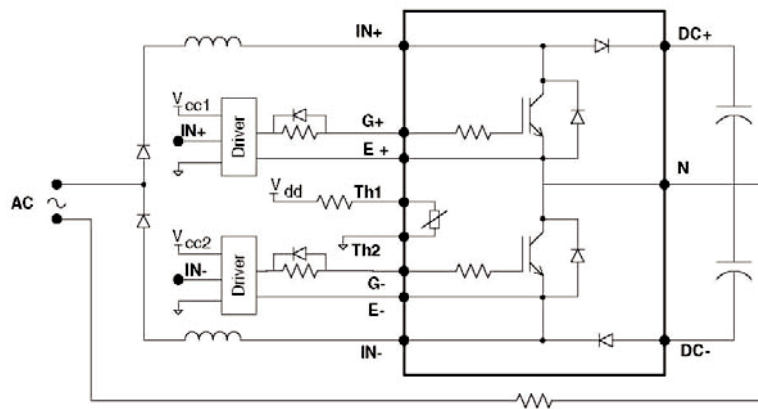


## ORDERING INFORMATION TABLE

Device code	<b>VS-</b>	<b>EM</b>	<b>G</b>	<b>050</b>	<b>J</b>	<b>60</b>	<b>N</b>
	①	②	③	④	⑤	⑥	⑦

- 1** - Vishay Semiconductors product
- 2** - Package indicator (EM = EMIPAK2)
- 3** - Circuit configuration (G = Dual mode PFC)
- 4** - Current rating (050 = 50 A)
- 5** - Die technology (J = Warp2 IGBT)
- 6** - Voltage rating (60 = 600 V)
- 7** - N = Ultrafast

## TYPICAL CONNECTION

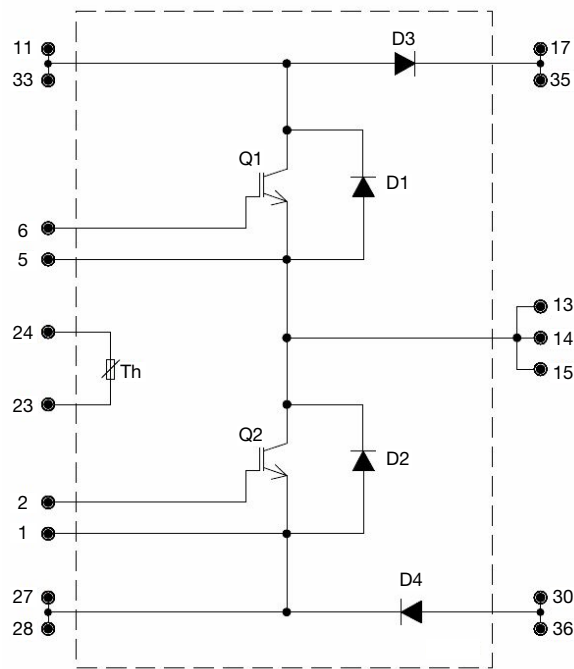


### Note

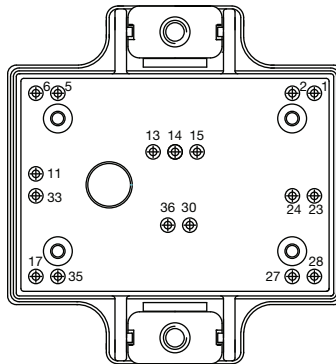
- Please refer to lead assignment for correct pin configuration. This diagram shows electrical connections only.



**CIRCUIT CONFIGURATION**



**PACKAGE**



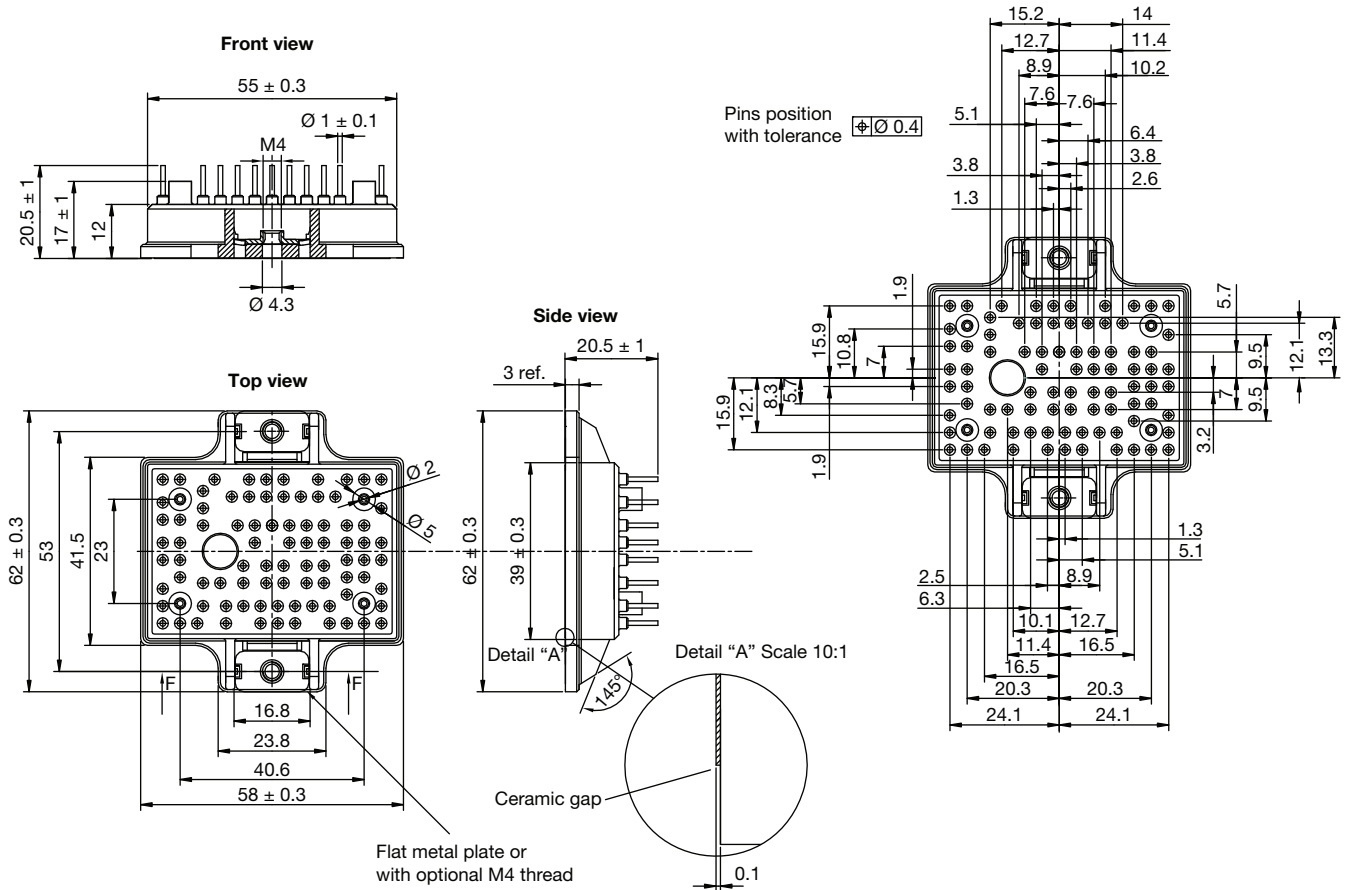
**LINKS TO RELATED DOCUMENTS**

Dimensions

[www.vishay.com/doc?95436](http://www.vishay.com/doc?95436)

## EMIPAK2

**DIMENSIONS** in millimeters





## Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

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